

Application Serial No. 10/618,955  
Reply to Office Action of December 22, 2004

PATENT  
Docket: CU-3290

### **Amendments To The Claims**

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

#### **Listing of claims:**

1. (currently amended) A test vehicle ball grid array package comprising:
  - a PCB having bonding fingers;
  - an adhesive material being coated on an edge of the PCB;
  - a sealing post being adhered on the adhesive material, **wherein an extrusion is formed at a upper end of the sealing post;**
    - a semiconductor testing chip having a plurality of bonding pads adhered on the PCB;
    - a plurality of metal wires separately connecting bonding pads of the PCB to the bonding fingers of the PCB;
    - a sealing cap adhered on a sealing post for sealing the semiconductor chip, **wherein the sealing cap is adhered on the extrusion of the sealing post;** and
    - a plurality of solder balls adhered to a lower side of the PCB.
2. (original) A test vehicle ball grid array package according to claim 1, wherein each of the sealing post and the sealing cap is made from non-conductive material.
- 3-4. (cancelled)
5. (original) A test vehicle ball grid array package according to claim 4, wherein the sealing cap is adhered on the extrusion of the sealing post by a low temperature thermoplastic tape or a material similar to low temperature thermoplastic tape.

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6. (original) A test vehicle ball grid array package according to claim 1, wherein the semiconductor chip is a center pad-type chip or an edge pad-type chip.